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Chung

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(54) **CONNECTIVITY MODULE FOR DATA LINK**

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(73) Assignee: **Aten International Co., Ltd.**, Taipei (TW)

(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **14-02**
(52) **U.S. Cl.** **D14/433**; D13/133
(58) **Field of Search** D14/432, 433; D13/123, 133, 135, 145, 147, 154; 439/284, 290, 591, 708, 660, 502

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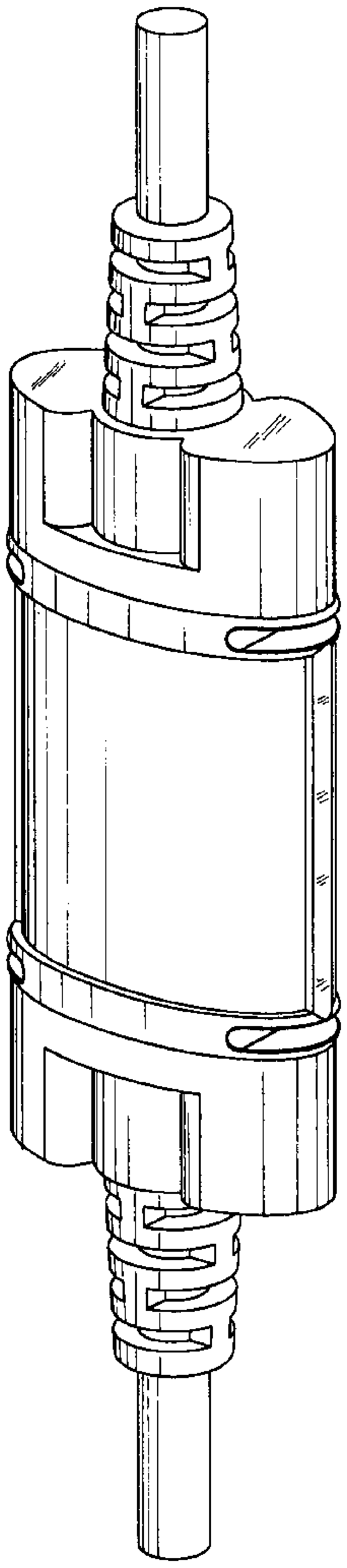
(57) **CLAIM**

The ornamental design for a connectivity module for data link, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a connectivity module for data link, showing my new design;
FIG. **2** is a front elevation view thereof, the rear elevation view being a mirror imgae of that shown;
FIG. **3** is a left side elevation view thereof, the right side elevation view being a mirror image of that shown; and,
FIG. **4** is a top plan view thereof, the bottom plan view being a mirror image of that shown.

1 Claim, 3 Drawing Sheets



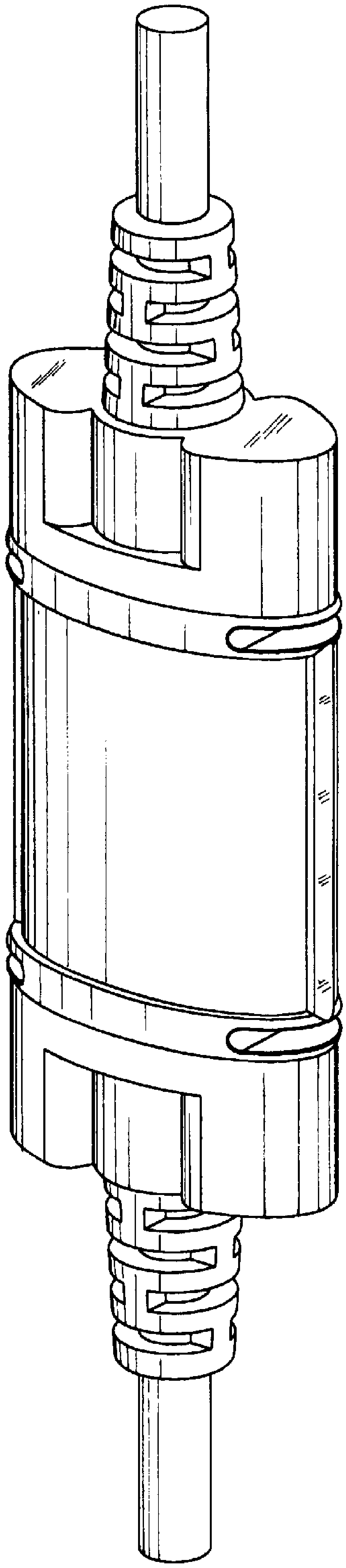


FIG.1

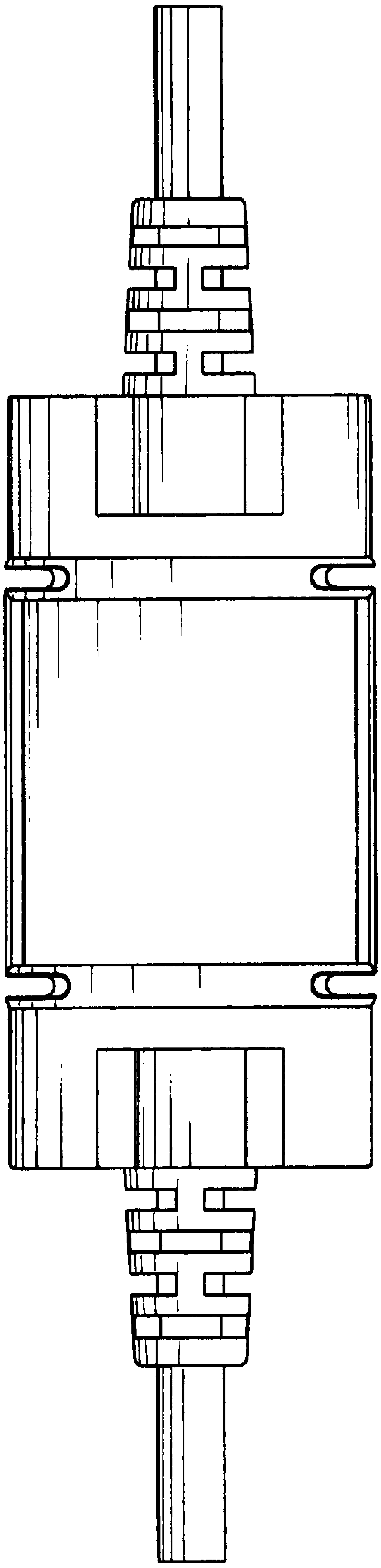


FIG.2

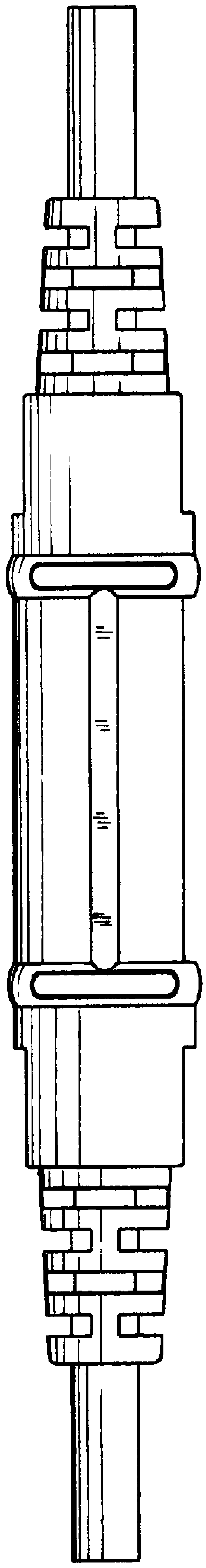


FIG.3

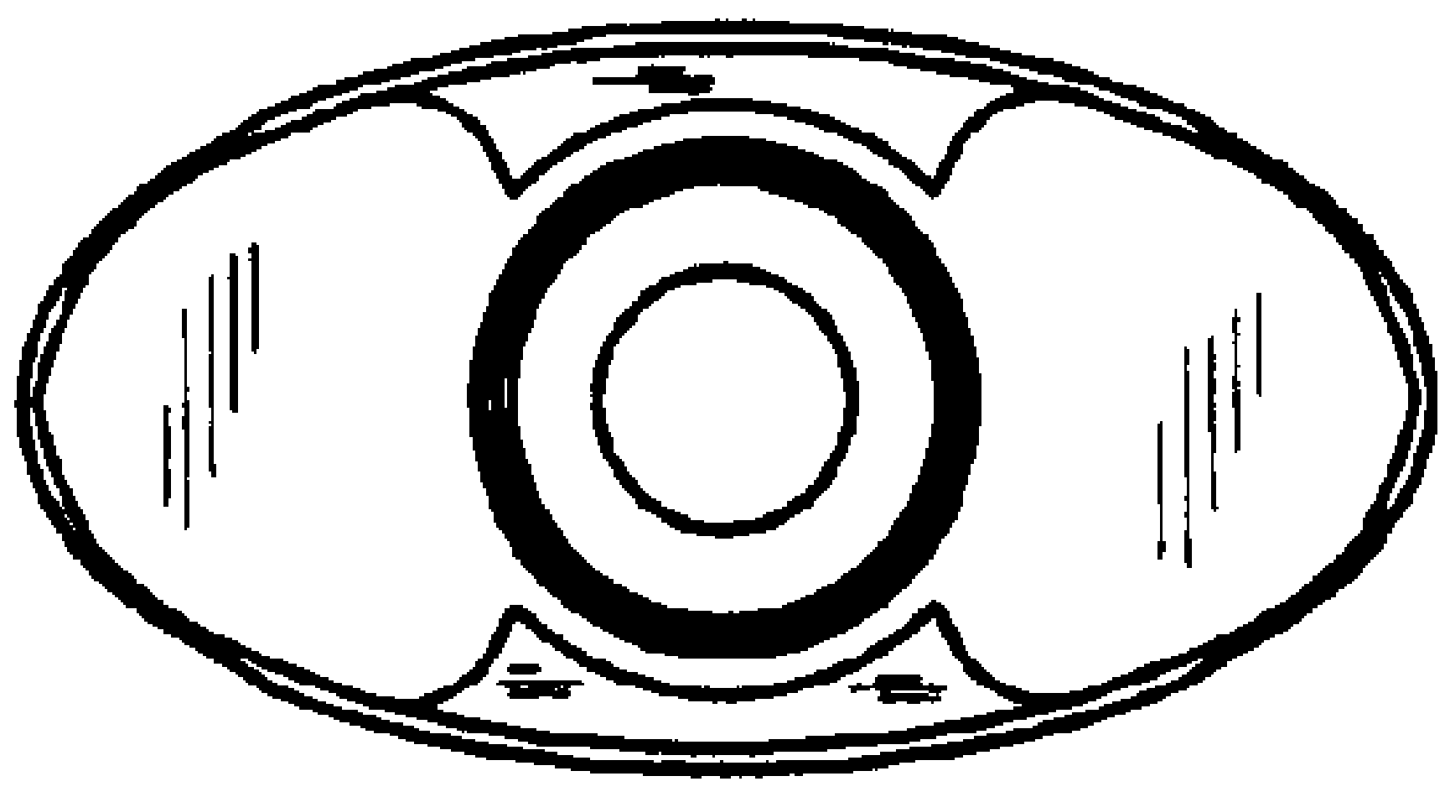


FIG.4